

# DATA SHEET

## **TDA8510J**

**26 W BTL and 2 × 13 W SE power  
amplifiers**

Preliminary specification  
Supersedes data of 1999 Jun 14  
File under Integrated Circuits, IC01

1999 Dec 14

## 26 W BTL and 2 × 13 W SE power amplifiers

## TDA8510J

### FEATURES

- Requires very few external components
- High output power
- Low output offset voltage (BTL channel)
- Fixed gain
- Diagnostic facility (distortion, short-circuit and temperature detection)
- Good ripple rejection
- Mode select switch (operating, mute and standby)
- AC and DC short-circuit safe to ground and to  $V_P$
- Low power dissipation in any short-circuit condition
- Thermally protected
- Reverse polarity safe

- Electrostatic discharge protection
- No switch-on/switch-off plop
- Flexible leads
- Low thermal resistance
- Identical inputs (inverting and non-inverting).

### GENERAL DESCRIPTION

The TDA8510J is an integrated class-B output amplifier in a 17-lead single-in-line (SIL) power package. It contains a 26 W Bridge-Tied Load (BTL) amplifier and 2 × 13 W Single-Ended (SE) amplifiers.

The device is primarily developed for multi-media applications and active speaker systems (stereo with subwoofer).

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>General</b>						
$V_P$	supply voltage		6	15	18	V
$I_{ORM}$	repetitive peak output current		–	–	4	A
$I_{q(tot)}$	total quiescent current		–	80	–	mA
$I_{stb}$	standby current		–	0.1	100	$\mu$ A
<b>BTL channel</b>						
$P_o$	output power	$R_L = 4 \Omega$ ; THD = 10%	–	26	–	W
SVRR	supply voltage ripple rejection		46	–	–	dB
$V_{n(o)}$	noise output voltage	$R_s = 0 \Omega$	–	70	–	$\mu$ V
$ Z_i $	input impedance		25	–	–	k $\Omega$
$ \Delta V_{OO} $	DC output offset voltage		–	–	150	mV
<b>Single-ended channels</b>						
$P_o$	output power	THD = 10% $R_L = 4 \Omega$ $R_L = 2 \Omega$	– –	7 13	– –	W W
SVRR	supply voltage ripple rejection		46	–	–	dB
$V_{n(o)}$	noise output voltage	$R_s = 0 \Omega$	–	50	–	$\mu$ V
$ Z_i $	input impedance		50	–	–	k $\Omega$

### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
TDA8510J	DBS17P	plastic DIL-bent-SIL power package; 17 leads (lead length 12 mm)	SOT243-1

# 26 W BTL and 2 × 13 W SE power amplifiers

## TDA8510J

### BLOCK DIAGRAM

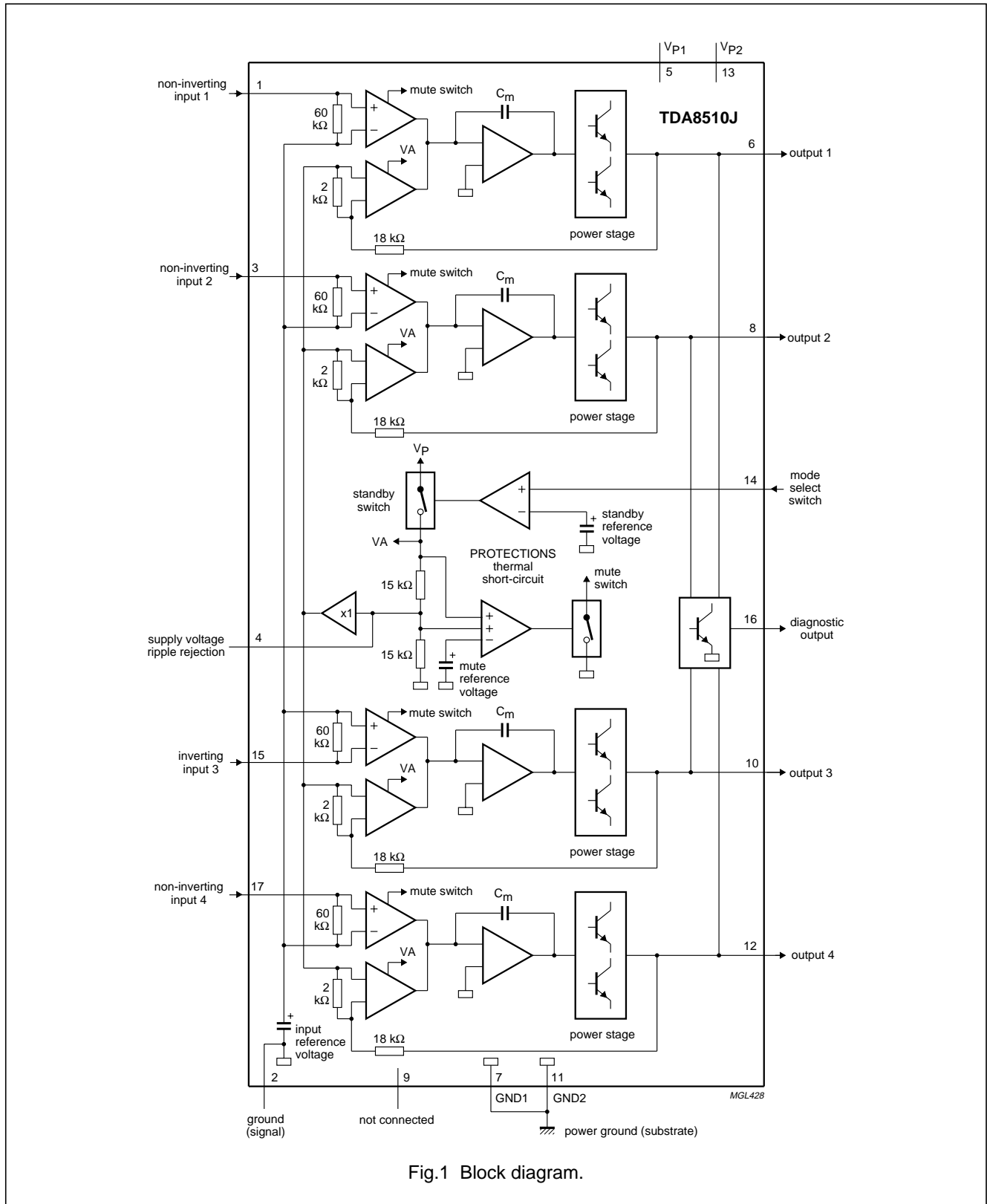


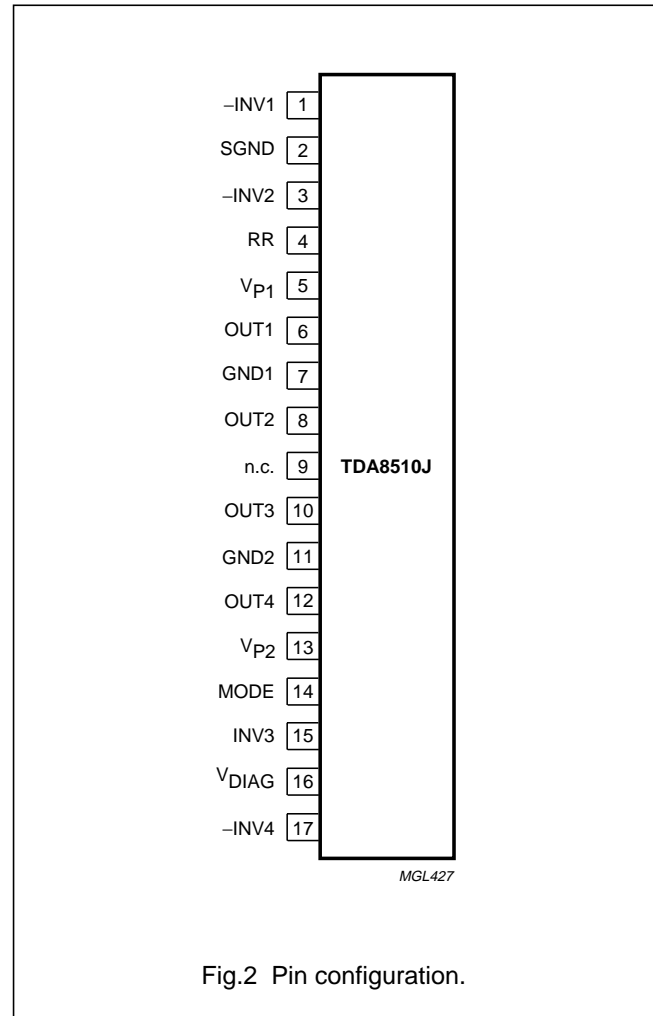
Fig.1 Block diagram.

# 26 W BTL and 2 × 13 W SE power amplifiers

## TDA8510J

### PINNING

SYMBOL	PIN	DESCRIPTION
-INV1	1	non-inverting input 1
SGND	2	signal ground
-INV2	3	non-inverting input 2
RR	4	supply voltage ripple rejection
V <sub>P1</sub>	5	supply voltage 1
OUT1	6	output 1
GND1	7	power ground 1
OUT2	8	output 2
n.c.	9	not connected
OUT3	10	output 3
GND2	11	power ground 2
OUT4	12	output 4
V <sub>P2</sub>	13	supply voltage 2
MODE	14	mode select switch input
INV3	15	inverting input 3
V <sub>DIAG</sub>	16	diagnostic output
-INV4	17	non-inverting input 4



## 26 W BTL and 2 × 13 W SE power amplifiers

### TDA8510J

#### FUNCTIONAL DESCRIPTION

The TDA8510J contains four identical amplifiers and can be used for two Single-Ended (SE) channels (fixed gain 20 dB) and one Bridge-Tied Load (BTL) channel (fixed gain 26 dB). Special features of the device are:

##### Mode select switch (pin 14)

- Low standby current (<100  $\mu$ A)
- Low switching current (low cost supply switch)
- Mute facility.

To avoid switch-on plops, it is advised to keep the amplifier in the mute mode during  $\geq 100$  ms (charging of the input capacitors at pins 1, 3, 15 and 17). This can be achieved by:

- Microcontroller control
- External timing circuit (see Fig.8).

##### Diagnostic output (pin 16)

###### DYNAMIC DISTORTION DETECTOR (DDD)

At the onset of clipping of one or more output stages, the dynamic distortion detector becomes active and pin 16 goes LOW. This information can be used to drive a sound processor or DC volume control to attenuate the input signal and thus limit the distortion. The output level of pin 16 is independent of the number of channels that are clipping (see Figs 3 and 4).

###### SHORT-CIRCUIT PROTECTION

When a short-circuit occurs at one or more outputs to ground or to the supply voltage, the output stages are switched off until the short-circuit is removed and the device is switched on again, with a delay of approximately 20 ms, after removal of the short-circuit. During this short-circuit condition, pin 16 is continuously LOW.

When a short-circuit across the load of one or more channels occurs the output stages are switched off for approximately 20 ms. After that time it is checked during approximately 50  $\mu$ s to see whether the short-circuit is still present. Due to this duty cycle of 50  $\mu$ s/20 ms the average current consumption during this short-circuit condition is very low (approximately 40 mA).

During this short-circuit condition, pin 16 is LOW for 20 ms and HIGH for 50  $\mu$ s (see Fig.5).

The power dissipation in any short-circuit condition is very low.

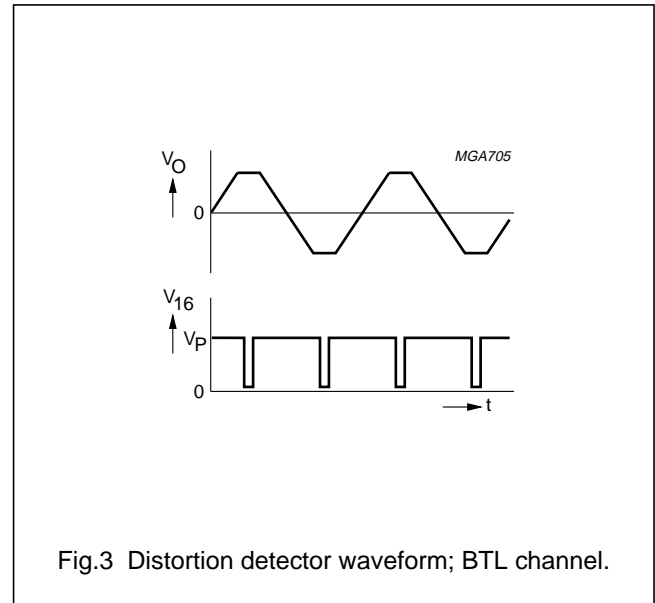


Fig.3 Distortion detector waveform; BTL channel.

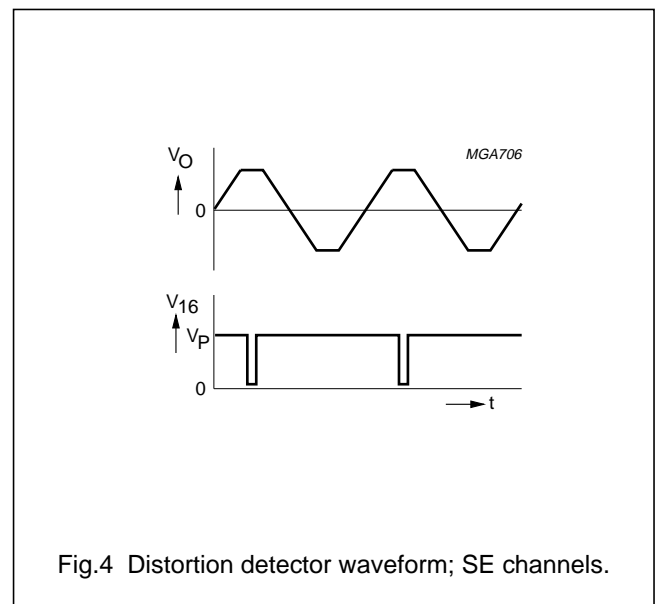


Fig.4 Distortion detector waveform; SE channels.

26 W BTL and 2 × 13 W SE power amplifiers

TDA8510J

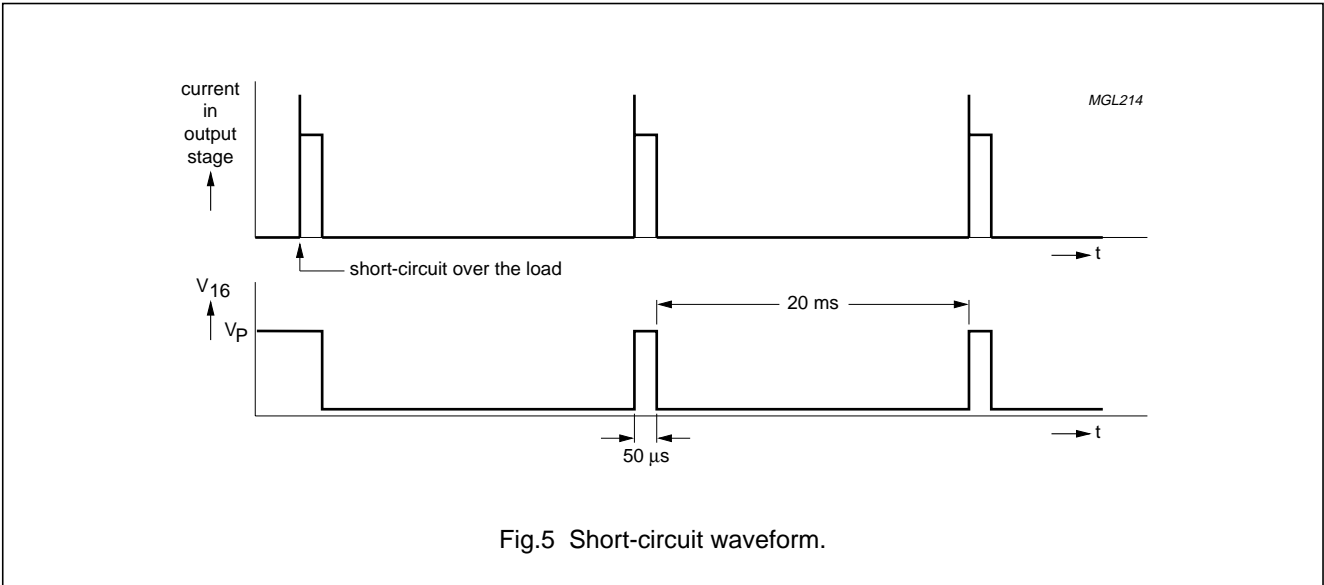


Fig.5 Short-circuit waveform.

TEMPERATURE DETECTION

When the virtual junction temperature  $T_{vj}$  reaches 150 °C, pin 16 will be active LOW.

OPEN-COLLECTOR OUTPUT

Pin 16 is an open-collector output, which allows pin 16 of more devices being tied together.

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>P</sub>	supply voltage	operating	–	18	V
		no signal	–	20	V
I <sub>OSM</sub>	non-repetitive peak output current		–	6	A
I <sub>ORM</sub>	repetitive peak output current		–	4	A
V <sub>sc</sub>	AC and DC short-circuit safe voltage		–	18	V
V <sub>rp</sub>	reverse polarity voltage		–	6	V
P <sub>tot</sub>	total power dissipation		–	60	W
T <sub>stg</sub>	storage temperature		–55	+150	°C
T <sub>amb</sub>	operating ambient temperature		–40	+85	°C
T <sub>vj</sub>	virtual junction temperature		–	150	°C

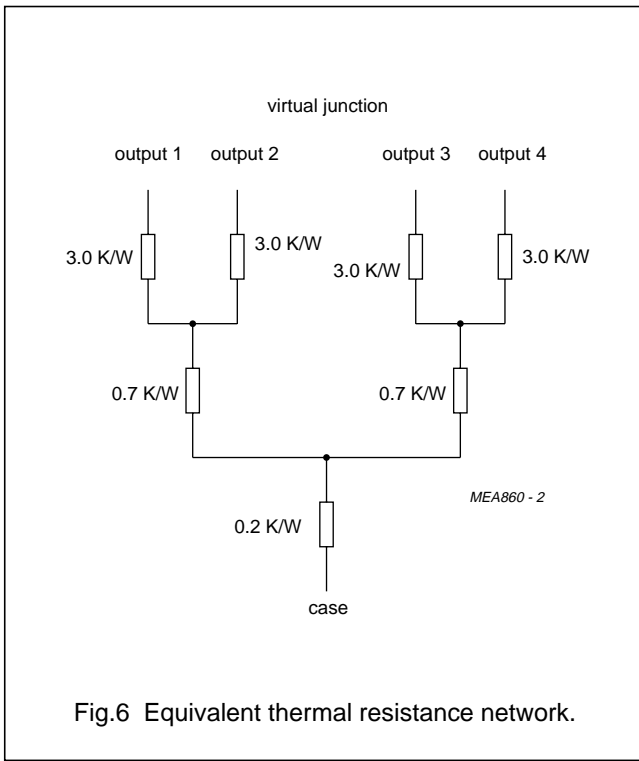
**THERMAL CHARACTERISTICS**

In accordance with IEC 747-1.

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	40	K/W
R <sub>th(j-c)</sub>	thermal resistance from junction to case (see Fig.6)		1.3	K/W

# 26 W BTL and 2 × 13 W SE power amplifiers

TDA8510J



## 26 W BTL and 2 × 13 W SE power amplifiers

TDA8510J

### DC CHARACTERISTICS

$V_P = 15\text{ V}$ ;  $T_{\text{amb}} = 25\text{ °C}$ ; measured in Fig.7; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Supply</b>						
$V_P$	supply voltage	note 1	6	15	18	V
$I_{q(\text{tot})}$	total quiescent current		–	80	160	mA
$V_O$	DC output voltage		–	6.9	–	V
$ \Delta V_{OO} $	DC output offset voltage	note 2	–	–	150	mV
<b>Mode select switch</b>						
$V_{\text{SW}(\text{on})}$	switch-on voltage level		8.5	–	–	V
<b>MUTE CONDITION</b>						
$V_{\text{mute}}$	mute voltage		3.3	–	6.4	V
$V_O$	output voltage in mute position	$V_{I(\text{max})} = 1\text{ V}$ ; $f = 1\text{ kHz}$	–	–	2	mV
$ \Delta V_{OO} $	DC output offset voltage	note 2	–	–	150	mV
<b>STANDBY CONDITION</b>						
$V_{\text{stb}}$	standby voltage		0	–	2	V
$I_{\text{stb}}$	standby current		–	–	100	$\mu\text{A}$
$I_{\text{sw}(\text{on})}$	switch-on current		–	12	40	$\mu\text{A}$
<b>Diagnostic output (pin 16)</b>						
$V_{\text{DIAG}}$	diagnostic output voltage	any short-circuit or clipping	–	–	0.6	V

### Notes

1. The circuit is DC adjusted at  $V_P = 6$  to  $18\text{ V}$  and AC operating at  $V_P = 8.5$  to  $18\text{ V}$ .
2. Only for BTL channel ( $V_{12-10}$ ).



## 26 W BTL and 2 × 13 W SE power amplifiers

TDA8510J

### AC CHARACTERISTICS

$V_P = 15\text{ V}$ ;  $f = 1\text{ kHz}$ ;  $T_{amb} = 25\text{ °C}$ ; measure in Fig.7; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>BTL channel</b>						
$P_o$	output power	note 1				
		THD = 0.5%	16	20	–	W
		THD = 10%	22	26	–	W
THD	total harmonic distortion	$P_o = 1\text{ W}$	–	0.06	–	%
B	power bandwidth	THD = 0.5%; $P_o = -1\text{ dB}$ ; with respect to 16 W	–	20 to 15000	–	Hz
$f_{ro(l)}$	low frequency roll-off	at $-1\text{ dB}$ ; note 2	–	25	–	Hz
$f_{ro(h)}$	high frequency roll-off	at $-1\text{ dB}$	20	–	–	kHz
$G_v$	closed loop voltage gain		25	26	27	dB
SVRR	supply voltage ripple rejection	note 3				
		on	48	–	–	dB
		mute	46	–	–	dB
		standby	80	–	–	dB
$ Z_i $	input impedance		25	30	38	k $\Omega$
$V_{n(o)}$	noise output voltage	on; $R_s = 0\ \Omega$ ; note 4	–	70	–	$\mu\text{V}$
		on; $R_s = 10\text{ k}\Omega$ ; note 4	–	100	200	$\mu\text{V}$
		mute; notes 4 and 5	–	60	–	$\mu\text{V}$
$\alpha_{cs}$	channel separation	$R_s = 10\text{ k}\Omega$	40	60	–	dB
<b>DYNAMIC DISTORTION DETECTOR</b>						
THD	total harmonic distortion	$V_{16} \leq 0.6\text{ V}$ ; no short-circuit	–	10	–	%

## 26 W BTL and 2 × 13 W SE power amplifiers

TDA8510J

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Single-ended channels</b>						
$P_o$	output power	note 1				
		THD = 0.5%	8	10	–	W
		THD = 10%	11	13	–	W
		$R_{L1} = 4 \Omega$ ; note 1				
		THD = 0.5%	–	5.5	–	W
		THD = 10%	–	7	–	W
THD	total harmonic distortion	$P_o = 1 \text{ W}$	–	0.06	–	%
$f_{ro(l)}$	low frequency roll-off	at –1 dB; note 2	–	25	–	Hz
$f_{ro(h)}$	high frequency roll-off	at –1 dB	20	–	–	kHz
$G_v$	closed loop voltage gain		19	20	21	dB
SVRR	supply voltage ripple rejection	note 3				
		on	48	–	–	dB
		mute	46	–	–	dB
		standby	80	–	–	dB
$ Z_i $	input impedance		50	60	75	k $\Omega$
$V_{n(o)}$	noise output voltage	on; $R_s = 0 \Omega$ ; note 4	–	50	–	$\mu\text{V}$
		on; $R_s = 10 \text{ k}\Omega$ ; note 4	–	70	100	$\mu\text{V}$
		mute; notes 4 and 5	–	50	–	$\mu\text{V}$
$\alpha_{cs}$	channel separation	$R_s = 10 \text{ k}\Omega$	40	60	–	dB
$ \Delta G_v $	channel unbalance		–	–	1	dB
<b>DYNAMIC DISTORTION DETECTOR</b>						
THD	total harmonic distortion	$V_{16} \leq 0.6 \text{ V}$ ; no short-circuit	–	10	–	%

### Notes

- Output power is measured directly at the output pins of the IC.
- Frequency response externally fixed.
- Ripple rejection measured at the output with a source impedance of 0  $\Omega$ , maximum ripple amplitude of 2 V (p-p) and at a frequency of between 100 Hz and 10 kHz.
- Noise measured in a bandwidth of 20 Hz to 20 kHz.
- Noise output voltage independent of  $R_s$  ( $V_i = 0 \text{ V}$ ).

26 W BTL and 2 × 13 W SE power amplifiers

TDA8510J

TEST AND APPLICATION INFORMATION

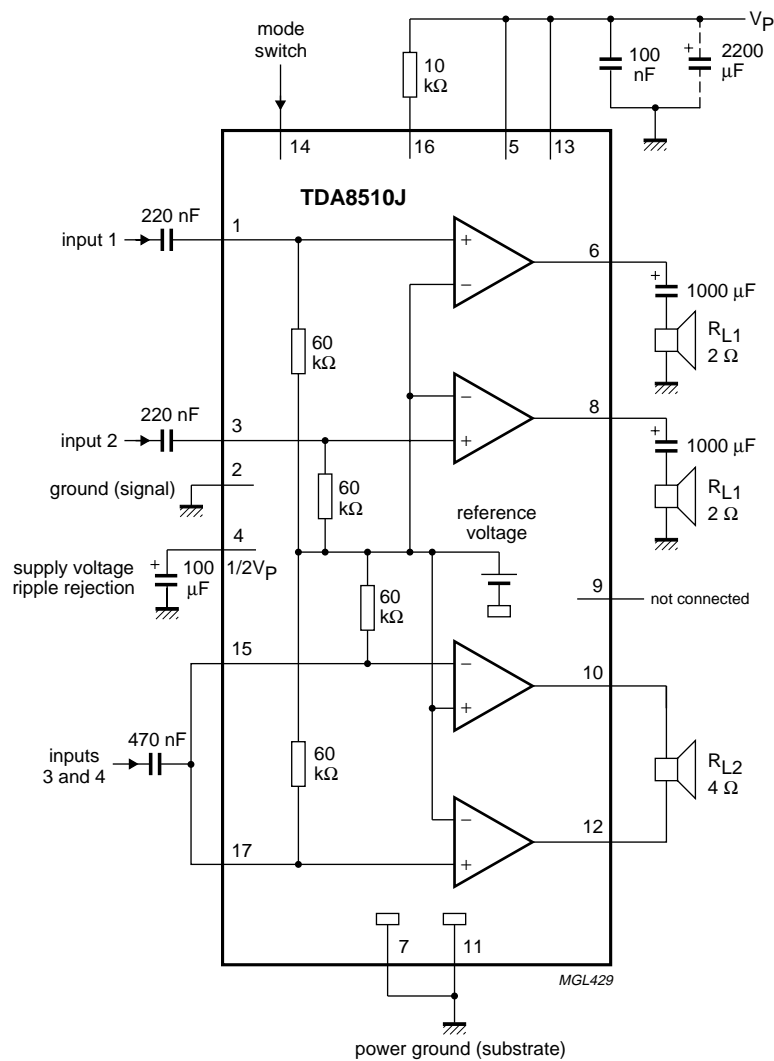


Fig.7 Application diagram.

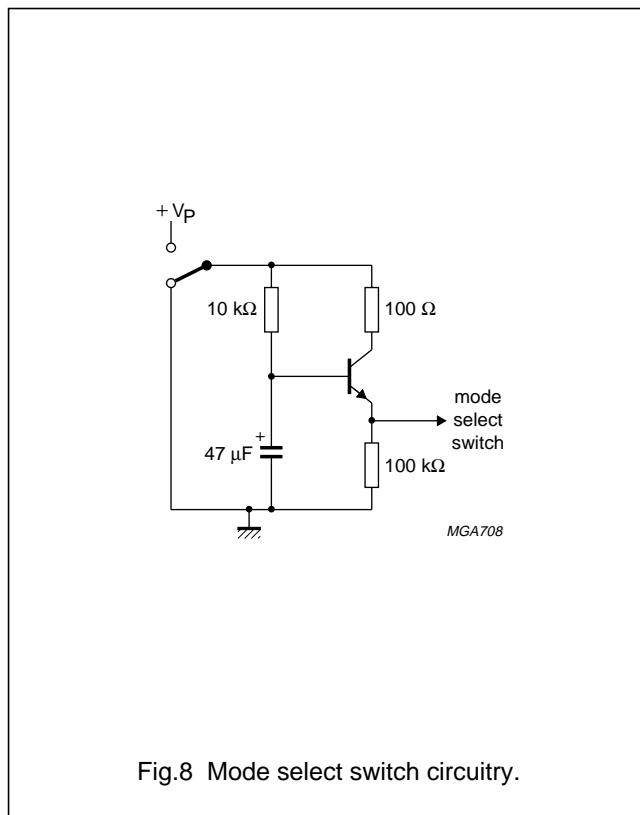
# 26 W BTL and 2 × 13 W SE power amplifiers

TDA8510J

## Mode select switch

To avoid switch-on plops, it is advised to keep the amplifier in the mute mode during >100 ms (charging of the input capacitors at pins 1, 3, 15 and 17).

The circuit in Fig.8 slowly ramps up the voltage at the mode select switch pin when switching on and results in fast muting when switching off.



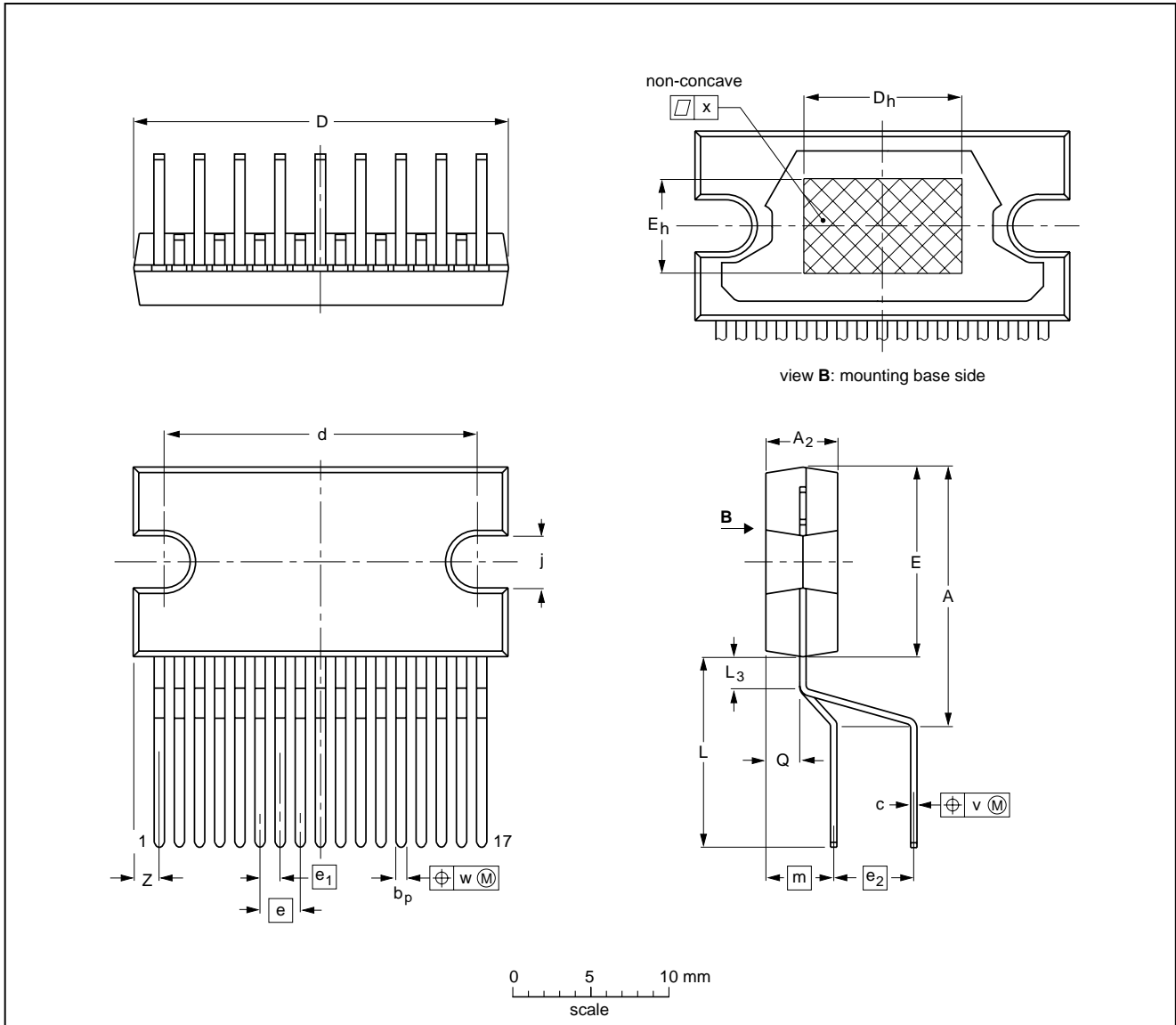
# 26 W BTL and 2 × 13 W SE power amplifiers

TDA8510J

## PACKAGE OUTLINE

DBS17P: plastic DIL-bent-SIL power package; 17 leads (lead length 12 mm)

SOT243-1



**DIMENSIONS (mm are the original dimensions)**

UNIT	A	A <sub>2</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	d	D <sub>h</sub>	E <sup>(1)</sup>	e	e <sub>1</sub>	e <sub>2</sub>	E <sub>h</sub>	j	L	L <sub>3</sub>	m	Q	v	w	x	Z <sup>(1)</sup>
mm	17.0 15.5	4.6 4.2	0.75 0.60	0.48 0.38	24.0 23.6	20.0 19.6	10	12.2 11.8	2.54	1.27	5.08	6	3.4 3.1	12.4 11.0	2.4 1.6	4.3	2.1 1.8	0.8	0.4	0.03	2.00 1.45

**Note**  
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT243-1						95-03-11- 97-12-16

## 26 W BTL and 2 × 13 W SE power amplifiers

TDA8510J

### SOLDERING

#### Introduction to soldering through-hole mount packages

This text gives a brief insight to wave, dip and manual soldering. A more in-depth account of soldering ICs can be found in our "Data Handbook IC26; Integrated Circuit Packages" (document order number 9398 652 90011).

Wave soldering is the preferred method for mounting of through-hole mount IC packages on a printed-circuit board.

#### Soldering by dipping or by solder wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joints for more than 5 seconds.

The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ( $T_{stg(max)}$ ). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

#### Manual soldering

Apply the soldering iron (24 V or less) to the lead(s) of the package, either below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

#### Suitability of through-hole mount IC packages for dipping and wave soldering methods

PACKAGE	SOLDERING METHOD	
	DIPPING	WAVE
DBS, DIP, HDIP, SDIP, SIL	suitable	suitable <sup>(1)</sup>

#### Note

- For SDIP packages, the longitudinal axis must be parallel to the transport direction of the printed-circuit board.

### DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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26 W BTL and 2 × 13 W SE power  
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SCA 68

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